

LNPTM THERMOCOMPTM COMPOUND DF006LXN

DF006LXN

DESCRIPTION

LNP THERMOCOMP DF006LXN compound is based on Polycarbonate (PC) resin containing 30% glass fiber. Added features of this grade include: Low Extractables.

This material is food contact compliant in most jurisdictions – exceptions may exist, request a declaration for details.

| GENERAL INFORMATION | |
|-----------------------|---------------------------------------|
| Features | Food contact, High stiffness/Strength |
| Fillers | Glass Fiber |
| Polymer Types | Polycarbonate (PC) |
| Processing Techniques | Injection Molding |

| INDUSTRY | SUB INDUSTRY |
|----------------------------|-----------------------------------|
| Building and Construction | Building Component |
| Consumer | Personal Accessory |
| Electrical and Electronics | Mobile Phone - Computer - Tablets |
| Industrial | Electrical |

TYPICAL PROPERTY VALUES

Revision 20250404

| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|--|----------------|-------------------|--------------|
| MECHANICAL ⁽¹⁾ | | | |
| Tensile Stress, brk, Type I, 5 mm/min | 114 | MPa | ASTM D638 |
| Tensile Strain, yld, Type I, 5 mm/min | 2.7 | % | ASTM D638 |
| Tensile Strain, brk, Type I, 5 mm/min | 3.2 | % | ASTM D638 |
| Tensile Modulus, 50 mm/min | 8630 | MPa | ASTM D638 |
| Flexural Stress, brk, 1.3 mm/min, 50 mm span | 149 | MPa | ASTM D790 |
| Flexural Modulus, 1.3 mm/min, 50 mm span | 8230 | MPa | ASTM D790 |
| Tensile Stress, break, 5 mm/min | 114 | MPa | ISO 527 |
| Tensile Strain, break, 5 mm/min | 7.5 | % | ISO 527 |
| Flexural Stress | 185 | MPa | ISO 178 |
| Flexural Modulus, 2 mm/min | 7860 | MPa | ISO 178 |
| IMPACT ⁽¹⁾ | | | |
| Izod Impact, unnotched, 23°C | 914 | J/m | ASTM D4812 |
| Izod Impact, notched, 23°C | 144 | J/m | ASTM D256 |
| Izod Impact, unnotched 80*10*4 +23°C | 56 | kJ/m ² | ISO 180/1U |
| Izod Impact, notched 80*10*4 +23°C | 14 | kJ/m ² | ISO 180/1A |
| THERMAL ⁽¹⁾ | | | |
| HDT, 0.45 MPa, 3.2 mm, unannealed | 144 | °C | ASTM D648 |
| HDT, 1.82 MPa, 3.2mm, unannealed | 140 | °C | ASTM D648 |
| HDT/Bf, 0.45 MPa Flatw 80*10*4 sp=64mm | 145 | °C | ISO 75/Bf |

| PROPERTIES | TYPICAL VALUES | UNITS | TEST METHODS |
|---|----------------|-------------------|--------------|
| HDT/Af, 1.8 MPa Flatw 80*10*4 sp=64mm | 141 | °C | ISO 75 /Af |
| PHYSICAL ⁽¹⁾ | | | |
| Specific Gravity | 1.45 | - | ASTM D792 |
| Moisture Absorption, (23°C/50% RH/24 hrs) | 0.07 | % | ASTM D570 |
| Density | 1.45 | g/cm ³ | ISO 1183 |
| Moisture Absorption (23°C / 50% RH) | 0.07 | % | ISO 62 |
| INJECTION MOLDING ⁽²⁾ | | | |
| Drying Temperature | 120 | °C | |
| Drying Time | 4 | Hrs | |
| Maximum Moisture Content | 0.02 | % | |
| Melt Temperature | 305 – 325 | °C | |
| Front - Zone 3 Temperature | 320 – 330 | °C | |
| Middle - Zone 2 Temperature | 310 – 320 | °C | |
| Rear - Zone 1 Temperature | 295 – 305 | °C | |
| Mold Temperature | 80 – 110 | °C | |
| Back Pressure | 0.2 – 0.3 | MPa | |
| Screw Speed | 30 – 60 | rpm | |

(1) The information stated on Technical Datasheets should be used as indicative only for material selection purposes and not be utilized as specification or used for part or tool design.

(2) Injection Molding parameters are only mentioned as general guidelines. These may not apply or may need adjustment in specific situations such as low shot sizes, large part molding, thin wall molding and gas-assist molding.

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